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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/073,494	05/06/1998	PAI-HUNG PAN	2915.1US(96-	9834
7590 12/03/2004			EXAMINER	
	ALKOWSKI		VU, HUNG K	
TRASK BRITT & ROSSA PO BOX 2550			ART UNIT	PAPER NUMBER
SALT LAKE C	CITY, UT 84110		2811	

DATE MAILED: 12/03/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

				M	
 _		Application No.	Applicant(s)		
		09/073,494	PAN ET AL.		
	Office Action Summary	Examiner	Art Unit		
		Hung Vu	2811		
Period fo	The MAILING DATE of this communication a	ppears on the cover sheet	with the correspondence add	iress	
	OF REPLY STATUTORY PERIOD FOR REP	N V IS SET TO EXDIDE 2	MONTH(S) EDOM		
THE - External after - If the If NO - Failt Any	MAILING DATE OF THIS COMMUNICATION ensions of time may be available under the provisions of 37 CFR or SIX (6) MONTHS from the mailing date of this communication. e period for reply specified above is less than thirty (30) days, a red period for reply is specified above, the maximum statutory period ure to reply within the set or extended period for reply will, by staturely received by the Office later than three months after the mained patent term adjustment. See 37 CFR 1.704(b).	1.136(a). In no event, however, may eply within the statutory minimum of the will apply and will expire SIX (6) Moute, cause the application to become	a reply be timely filed nirty (30) days will be considered timely. DNTHS from the mailing date of this cor ABANDONED (35 U.S.C. § 133).		
Status					
1) 又	Responsive to communication(s) filed on 13	September 2004.			
·	· · · · · · · · · · · · · · · · · · ·	nis action is non-final.			
'=	Since this application is in condition for allow		atters, prosecution as to the	merits is	
closed in accordance with the practice under Ex parte Quayle, 1935 C.D. 11, 453 O.G. 213.					
Disposit	ion of Claims				
4)⊠	Claim(s) 23-26,29-31 and 34-44 is/are pendi	ng in the application.			
,	4a) Of the above claim(s) is/are withdr				
5)□	Claim(s) is/are allowed.				
6)⊠	Claim(s) 23-26,29-31 and 34-44 is/are reject	ed.			
7)	Claim(s) is/are objected to.				
8)[Claim(s) are subject to restriction and	or election requirement.			
Applicat	ion Papers				
9)[The specification is objected to by the Exami	ner.			
	The drawing(s) filed on is/are: a) address		o by the Examiner.		
	Applicant may not request that any objection to the	ne drawing(s) be held in abey	ance. See 37 CFR 1.85(a).		
	Replacement drawing sheet(s) including the corre	ection is required if the drawir	ng(s) is objected to. See 37 CF	R 1.121(d).	
11)	The oath or declaration is objected to by the	Examiner. Note the attach	ed Office Action or form PT0	O-152.	
Priority :	under 35 U.S.C. § 119				
12)	Acknowledgment is made of a claim for foreign	gn priority under 35 U.S.C.	. § 119(a)-(d) or (f).		
•	☐ All b)☐ Some * c)☐ None of:	. ,			
	1. Certified copies of the priority docume	nts have been received.			
	2. Certified copies of the priority docume	nts have been received in	Application No		
	3. Copies of the certified copies of the pr	iority documents have bee	n received in this National S	Stage	
	application from the International Bure	eau (PCT Rule 17.2(a)).			
* (See the attached detailed Office action for a li	st of the certified copies no	ot received.		
Attachmer	• •	∧ □	(DTO 442)		
	ce of References Cited (PTO-892) ce of Draftsperson's Patent Drawing Review (PTO-948)		v Summary (PTO-413) o(s)/Mail Date		
3) 🔯 Info	rmation Disclosure Statement(s) (PTO-1449 or PTO/SB/0 er No(s)/Mail Date		f Informal Patent Application (PTO	-152)	

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DETAILED ACTION

Claim Rejections - 35 USC § 103

- 1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 23-26, 29-31, 34-44 are rejected under 35 U.S.C. 103(a) as being unpatentable over Chen et al. (PN 5,472,896, of record) in view of Tomozawa et al. (PN 4,782,037, of record). With regard to claim 23, Chen et al. discloses a gate stack on a silicon substrate having a dielectric layer thereover, the dielectric layer being substantially devoid of pitting, the operable gate stack including a non-crystalline metallic silicide film (16) and a dielectric cap (22) on the non-crystalline metallic silicide film. Note Col. 4, lines 23-50 and Figures 1e and 3f. Also note that because a metallic silicide film (16) is in an amorphous state, it is inherent that the dielectric layer is substantially devoid of pitting.

Chen et al. discloses the dielectric cap is formed of oxide. Chen et al. does not disclose the dielectric cap is formed of silicon nitride. However, Tomozawa et al. discloses a dielectric cap (11) is formed of oxide or silicon nitride. Note Figures 1B and 9, and Col. 4, lines 45-54. Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to substitute the oxide of Chen et al. by the silicon nitride of Tomozawa et al. because oxide and silicon nitride are commonly used as the material for the dielectric cap and they are interchangeable.

Note that a term "the gate stack is operable" is a recitation of the intended use of the claimed invention which must result in a structural difference between the claimed invention and the prior art in order to patentably distinguish the claimed invention from the prior art. If the prior art structure is capable of performing the intended use, then it meets the claim. In a claim drawn to a process of making, the intended use must result in a manipulative difference as compared to the prior art. See *In re Casey*, 152 USPQ 235 (CCPA 1967) and *In re Otto*, 136 USPQ 458, 459 (CCPA 1963). The gate stack of Chen et al. and Tomozawa et al. is also operable.

With regard to claim 24, Chen et al. discloses a gate stack on a silicon substrate having a dielectric layer thereover, the dielectric layer being substantially devoid of pitting, the operable gate stack, including an amorphous metallic silicide film (16) wherein the metallic silicide film is substantially devoid of silicon clusters, a dielectric cap (22) on the non-crystalline metallic silicide film. Note Col. 4, lines 23-50 and Figures 1e and 3f. Also note that because the metallic silicide film is in an amorphous state, it is inherent that it is substantially devoid of silicon clusters and the dielectric layer is substantially devoid of pitting.

Chen et al. discloses the dielectric cap is formed of oxide. Chen et al. does not disclose the dielectric cap is formed of silicon nitride. However, Tomozawa et al. discloses a dielectric cap (11) is formed of oxide or silicon nitride. Note Figures 1B and 9, and Col. 4, lines 45-54. Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to substitute the oxide of Chen et al. by the silicon nitride of Tomozawa et al. because oxide and silicon nitride are commonly used as the material for the dielectric cap and they are interchangeable.

Note that a term "the gate stack is operable" is a recitation of the intended use of the claimed invention which must result in a structural difference between the claimed invention and the prior art in order to patentably distinguish the claimed invention from the prior art. If the prior art structure is capable of performing the intended use, then it meets the claim. In a claim drawn to a process of making, the intended use must result in a manipulative difference as compared to the prior art. See *In re Casey*, 152 USPQ 235 (CCPA 1967) and *In re Otto*, 136 USPQ 458, 459 (CCPA 1963). The gate stack of Chen et al. and Tomozawa et al. is also operable.

With regard to claim 25, Chen et al. discloses a gate stack on a silicon substrate (10) having a dielectric layer (12) thereover, the dielectric layer being substantially devoid of pitting, the operable gate stack comprising,

a polysilicon layer (14) disposed over the dielectric layer;

a non-crystalline metallic silicide film (16) disposed over the polysilicon layer; a dielectric cap (22) on the non-crystalline metallic silicide film. Note Col. 4, lines 23-50 and Figures 1e and 3f. Also note that because the metallic silicide film is in an amorphous state, it is inherent that it is substantially devoid of silicon clusters and the dielectric layer is substantially devoid of pitting.

Chen et al. discloses the dielectric cap is formed of oxide. Chen et al. does not disclose the dielectric cap is formed of silicon nitride. However, Tomozawa et al. discloses a dielectric cap (11) is formed of oxide or silicon nitride. Note Figures 1B and 9, and Col. 4, lines 45-54. Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to substitute the oxide of Chen et al. by the silicon nitride of Tomozawa et al. because

oxide and silicon nitride are commonly used as the material for the dielectric cap and they are interchangeable.

Note that a term "the gate stack is operable" is a recitation of the intended use of the claimed invention which must result in a structural difference between the claimed invention and the prior art in order to patentably distinguish the claimed invention from the prior art. If the prior art structure is capable of performing the intended use, then it meets the claim. In a claim drawn to a process of making, the intended use must result in a manipulative difference as compared to the prior art. See *In re Casey*, 152 USPQ 235 (CCPA 1967) and *In re Otto*, 136 USPQ 458, 459 (CCPA 1963). The gate stack of Chen et al. and Tomozawa et al. is also operable.

With regard to claim 26, Chen et al. discloses a gate stack structure comprising an operable gate stack on a dielectric layer (12), over a silicon substrate (10), wherein the dielectric layer is substantially devoid of pitting, the operable gate stack comprising a metallic silicide film (16) and a dielectric cap (22) on the metallic silicide film. Note that because a metallic silicide film (16) is in an amorphous state, it is inherent that the dielectric layer is substantially devoid of pitting. Note Col. 4, lines 23-50 and Figures 1e and 3f.

Chen et al. discloses the dielectric cap is formed of oxide. Chen et al. does not disclose the dielectric cap is formed of silicon nitride. However, Tomozawa et al. discloses a dielectric cap (11) is formed of oxide or silicon nitride. Note Figures 1B and 9, and Col. 4, lines 45-54. Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to substitute the oxide of Chen et al. by the silicon nitride of Tomozawa et al. because

oxide and silicon nitride are commonly used as the material for the dielectric cap and they are interchangeable.

Note that a term "the gate stack is operable" is a recitation of the intended use of the claimed invention which must result in a structural difference between the claimed invention and the prior art in order to patentably distinguish the claimed invention from the prior art. If the prior art structure is capable of performing the intended use, then it meets the claim. In a claim drawn to a process of making, the intended use must result in a manipulative difference as compared to the prior art. See In re Casey, 152 USPQ 235 (CCPA 1967) and In re Otto, 136 USPQ 458, 459 (CCPA 1963). The gate stack of Chen et al. and Tomozawa et al. is also operable.

With regard to claim 29, Chen et al. discloses a semiconductor device comprising at least one gate stack formed on a silicon substrate having a dielectric layer thereover, the dielectric layer being substantially devoid of pitting, the at least one gate stack comprising a non-crystalline metallic silicide film (16) and a dielectric cap (22) on the non-crystalline metallic silicide film. Note Col. 4, lines 23-50 and Figures 1e and 3f. Also note that because a metallic silicide film (16) is in an amorphous state, it is inherent that the dielectric layer is substantially devoid of pitting.

Chen et al. discloses the dielectric cap is formed of oxide. Chen et al. does not disclose the dielectric cap is formed of silicon nitride. However, Tomozawa et al. discloses a dielectric cap (11) is formed of oxide or silicon nitride. Note Figures 1B and 9, and Col. 4, lines 45-54. Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to substitute the oxide of Chen et al. by the silicon nitride of Tomozawa et al. because

oxide and silicon nitride are commonly used as the material for the dielectric cap and they are interchangeable.

With regard to claim 30, Chen et al. and Tomozawa et al. disclose the at least one gate stack further comprising,

a polysilicon layer (14) disposed over the dielectric layer,

the non-crystalline metallic silicide film (16) being disposed over the polysilicon layer.

With regard to claim 31, Chen et al. discloses a semiconductor device comprising at least one gate stack structure on a dielectric layer (12), over a silicon substrate (10), wherein the dielectric layer is substantially devoid of pitting, the at least one gate stack structure comprising a metallic silicide film (16) and a dielectric cap (22) on the metallic silicide film. Note Col. 4, lines 23-50 and Figures 1e and 3f. Also note that because a metallic silicide film (16) is in an amorphous state, it is inherent that the dielectric layer is substantially devoid of pitting.

Chen et al. discloses the dielectric cap is formed of oxide. Chen et al. does not disclose the dielectric cap is formed of silicon nitride. However, Tomozawa et al. discloses a dielectric cap (11) is formed of oxide or silicon nitride. Note Figures 1B and 9, and Col. 4, lines 45-54.

Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to substitute the oxide of Chen et al. by the silicon nitride of Tomozawa et al. because oxide and silicon nitride are commonly used as the material for the dielectric cap and they are interchangeable.

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Response to Arguments

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2. Applicant's arguments filed 02/02/04 and 09/13/04 have been fully considered but they are not persuasive.

It is argued, at pages 9-12 of the Remarks, that Chen et al. does not disclose the gate stack structure including an amorphous metallic silicide film. This argument is not convincing because Chen et al. disclose, as shown in Col. 4, lines 23-50 and Figures 1e and 3f, the gate stack structure including an amorphous metallic silicide film. Also note that because a metallic silicide film (16) is in an amorphous state, it is inherent that the dielectric layer is substantially devoid of pitting. Note that the examiner uses the intermediate structure of the gate stack before thermal treatment of the refractory metal silicide. The gate stack of Chen et al. and Tomozawa et al. is also operable since a term "the gate stack is operable" is a recitation of the intended use of the claimed invention which must result in a structural difference between the claimed invention and the prior art in order to patentably distinguish the claimed invention from the prior art. If the prior art structure is capable of performing the intended use, then it meets the claim. In a claim drawn to a process of making, the intended use must result in a manipulative difference as compared to the prior art. See In re Casey, 152 USPQ 235 (CCPA 1967) and In re Otto, 136 USPQ 458, 459 (CCPA 1963). The gate stack of Chen et al. and Tomozawa et al. is also operable. Therefore, Applicants' claims 23-26, 29-31, 34-44 do not distinguish over the Chen et al. in view of Tomozawa et al.

Conclusion

3. THIS ACTION IS MADE FINAL. Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Hung K. Vu whose telephone number is (571) 272-1666. The examiner can normally be reached on Mon-Thurs 6:00-3:30, alternate Friday 7:00-3:30, Eastern Time.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Eddie C. Lee can be reached on (571) 272-1732. The Central Fax Number for the organization where this application or proceeding is assigned is (703) 872-9306.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (703) 308-0956.

Vu

November 17, 2004

Hung Vu

Patent Examiner